



Final Product Change Notification

201504015F01

Issue Date: 08-Jun-2015
Effective Date: 20-Sep-2015

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QUALITY

Management Summary

2nd source for Black Coating (BC) of SOD962 products.

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

2nd source for Black Coating (BC) of SOD962 products

Details of this Change

Additional Black Coating (BC) processing at the already released bumping sites as 2nd source to NXP (in addition to NXP-Hamburg).

BC Material will stay the same at all manufacturing sites. 2nd source sites for NXP are released back-end suppliers in running mass-production.

For 3 products with PI (polyimide) layer (see attached document under files) the thickness measurement point will be standardized and the maximum PI layer thickness will be marginally increased.

Why do we Implement this Change

- Increase of production capacity and flexibility.
- Simplification of production flow
- Enhance process capability control (PI layer)

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 15-Sep-2015

Impact

No impact on form, fit or function

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

NXP will keep Hamburg site for production flexibility

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 08-Jul-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA customer support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors

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Changed Orderable Part#	Changed Part 12NC
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